

# Aging of Aluminium contacts to Ion-implanted Silicon Radiation Detector

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## Introduction

The aging effect of Aluminium contact made to silicon is a known problem in Si technology [1]. Because of the presence of native oxide on silicon, Al takes some time, depending on the temperature, to form intimate contact and form ohmic Al/n<sup>+</sup>- and Al/p<sup>+</sup>-Si contacts. Changes in the characteristics of ion-implanted silicon detectors with Al contacts due to this aging process are reported here.

## Al Contacts

Electrical nature of Al contacts made to ion-implanted p<sup>+</sup>- as well as n<sup>+</sup>-Si layer on hyper pure (~ 10 kΩ-cm) n-type Si<111> wafers, we use for detector fabrication, was investigated. Si samples were lapped and given a mirror polish by etching in CP4A. They were implanted with 25 keV-ions of <sup>11</sup>B<sup>+</sup> and <sup>31</sup>P<sup>+</sup> to the dose of 1x10<sup>15</sup>/cm<sup>2</sup> to prepare the p<sup>+</sup>- and n<sup>+</sup>-Si layers respectively. Dopant activation was carried out at 900 °C for 30 minutes in an open quartz tube under the flow of dry nitrogen. Two concentric Al contacts (see Fig.1(a)) with thickness of ~40 μg/cm<sup>2</sup> were deposited by thermal evaporation in vacuum (~1x10<sup>-5</sup> torr). Their areas were kept different (~1:3) to see the contact-area dependent (non-ohmic) nature of the I-V characteristics at low bias voltage.

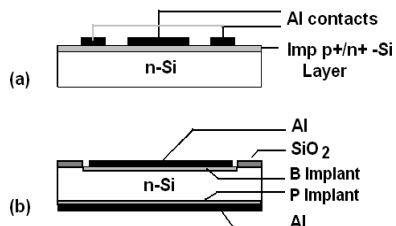


Fig.1 . Schematics of: (a) Contact test structure and (b) Ion-imp Si diode (detector).

I-V characteristics (see Figs. 2 & 3) of the contacts were measured in vacuum (~1x10<sup>-1</sup> torr) at room temperature. The as-evaporated Al/p<sup>+</sup>-Si contacts showed linear characteristics with slope increasing over a period of 1 week. It indicated the lowering of the effective metal-semiconductor barrier height due to the aging process. A low temperature heat treatment was given at ~350 °C for 30 minutes under the flow of dry nitrogen to accelerate the aging process. As expected, it helped in lowering the Al/p<sup>+</sup>- Si contact resistance further.

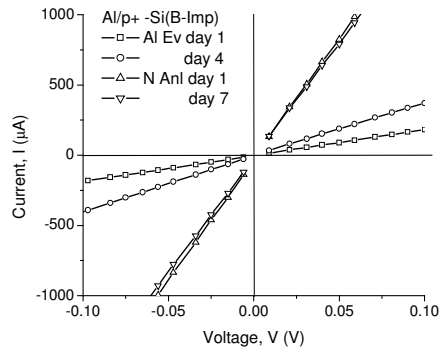


Fig.2. I-V characteristics of Al/p<sup>+</sup>-Si contact.

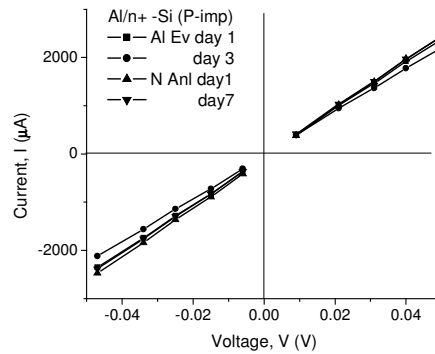


Fig.3. I-V characteristics of Al/n<sup>+</sup>-Si contact.

In case of the Al/n<sup>+</sup> contacts, almost no change in linearity and slope of their characteristics, even after giving the low temperature treatment, was observed. The barrier height for the implanted n<sup>+</sup> layer seems to be large enough to cause efficient tunneling and make the Al/n<sup>+</sup>-Si contact ohmic [1].

### Ion-implanted Detectors

Oxide passivated ion-implanted silicon radiation detectors having active area of about 100 cm<sup>2</sup> were fabricated from the high-resistivity n-type material by following the procedure reported earlier [2]. The schematic of the p<sup>+</sup>/n/n<sup>+</sup> detector (diode) structure with Al contacts is given in Fig.1(b). Samples were thermally oxidized at 1050 °C to prepare the ~0.6 μ thick silicon oxide. Circular type of windows was opened to implant the boron ions to make the passivated rectifying junction. The n<sup>+</sup> and p<sup>+</sup> layers were prepared by following the same procedure used to test the Al/p<sup>+</sup> and Al/n<sup>+</sup>-Si contact structures. Al contacts were evaporated as already mentioned.

Detectors were tested for their reverse as well as forward characteristics (see Figs. 4 & 5) at room temperature in vacuum. The leakage current was seen dropping with time. A low temperature annealing at ~350 °C helped in reducing the leakage further to a stable level. The dropping of the barrier height of the Al/p<sup>+</sup>-Si contact with time is thought to help in reducing the injection of minority carriers to the p-type region that contributes to the leakage.

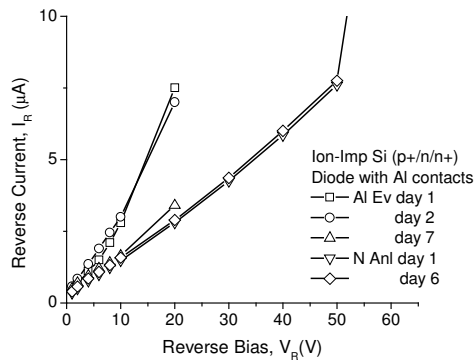


Fig.4. Reverse I-V characteristics of ion-implanted Si detector .

The low temperature treatment changed the forward characteristics drastically. It resulted in lowering the series resistance, mostly due to the drop in resistance of the Al/p<sup>+</sup>-Si contact.

There was improvement in the performance (leakage, energy resolution and timing) of the implanted Si detectors (see Fig.6) due to the aging of the Al/p<sup>+</sup> contacts.

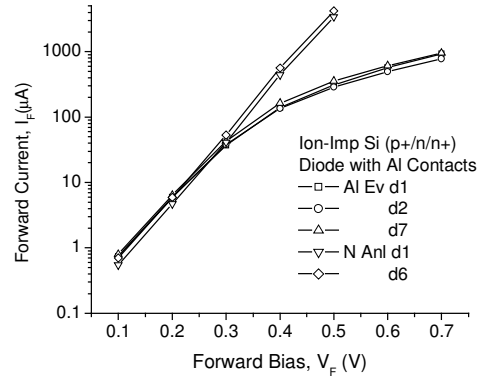


Fig.5. Forward I-V characteristics of Si detector.

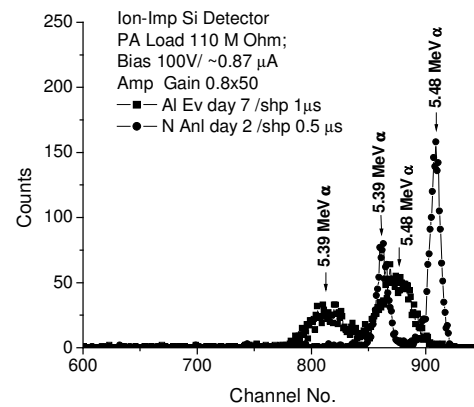


Fig.6. <sup>242</sup>Am –<sup>239</sup>Pu alpha spectra.

### Acknowledgement:

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### References

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- [2] R. Prasad and D. Sahoo, DAE Nucl. Phys. Symp. 45B(2002)422.